

Title (en)  
METHOD FOR PRODUCING A CHIP MODULE

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINES CHIPMODULS

Title (fr)  
PROCÉDÉ DE FABRICATION D'UN MODULE DE PUCE

Publication  
**EP 3087592 A2 20161102 (DE)**

Application  
**EP 14815258 A 20141125**

Priority  
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• EP 2014075518 W 20141125

Abstract (en)  
[origin: WO2015096946A2] The invention concerns a method for producing a chip module (90) having a carrier substrate and at least one chip arranged on the carrier substrate, as well as a contact conductor arrangement (45) for connecting chip pads to contacts (69, 70, 71) arranged on a contact face (56) of the chip module, in which method the front face of the chip which is provided with the chip pads is secured to the carrier substrate and then the contact conductor arrangement is formed by structuring of a contact material layer of the carrier substrate.

IPC 8 full level  
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CPC (source: CN EP US)  
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See references of WO 2015096946A2

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